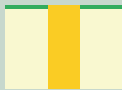




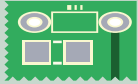
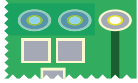
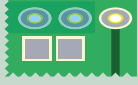

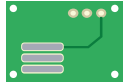


CAPABILITIES

ITEM		STANDARD		TOLERANCE
TYPE OF CIRCUIT	-	Single sided	Single sided	NA
MATERIALS	-	FR4, CEM1, CEM3	IMS aluminium	NA
SOLDERMASK	-	Green, White, Black	Green, White, Black	NA
SILKSCREEN	-	White, Black	White, Black	NA
BASE COPPER THICKNESS	-	18 - 35 - 70 - 105 µm	35 - 70 - 105 µm	NA
FINISHINGS	Immersion tin	1.0 - 1.3 µm	NA	-
	Immersion silver	0.15 - 0.5 µm	0.15 - 0.5 µm	
	HAL Pb free	1.5 - 10 µm	1.5 - 10 µm	
	OSP	√	√	
	ENIG	Ni 4-7 µm, Au 0.05 - 0.12 µm	Ni 4-7 µm, Au 0.05 - 0.12 µm	
	Plated Gold	Ni 4-7 µm, Au 0.5 - 1 µm	NA	
PCB THICKNESS		0.3 – 3.2 mm	0.5 – 2.5 mm	± 10%
MINIMUM DIAMETER NPTH		0.6 mm	1 mm	± 0.05 mm
MINIMUM ANULAR RING		0.18 mm	NA	± 15% (18 µm)
MINIMUM WITH/SPACE OF TRACK – DEPENDING UPON BASE Cu T.		18 µm - 0.12 mm	-	± 15% (18 µm)
		35 µm - 0.15 mm	35 µm - 0.18 mm	± 20% (35 µm)
		70 µm - 0.19 mm	70 µm - 0.21 mm	± 25% (70 µm)
SOLDERMASK THICKNESS	-	> 10 µm	> 10 µm	NA
MINIMUM SOLDERMASK DAM		0.2 mm	0.2 mm	NA
MINIMUM SILKSCREEN LINE		0.2 mm	0.2 mm	NA
MAXIMUM DIAMETER COVERED BY PEELABLE MASK		Ø : 2.5 mm	NA	NA
DISTANCE FROM PEELABLE TO OTHER PADS		1 mm	NA	NA
MINIMUM CORE THICKNESS (SCORING)		0.5 mm	0.35 mm (asymmetric)	± 0.1 mm
TOLERANCE POSITION SCORING	-	± 0.5 mm		
TOLERANCE ROUTING		$\leq 50 \text{ mm} \pm 0.1$ $> 50 \text{ mm} / < 200 \text{ mm} \pm 0.15$ $\geq 200 \text{ mm} \pm 0.2$		
WARPAGE	-	< 0.75%	< 0.75%	NA